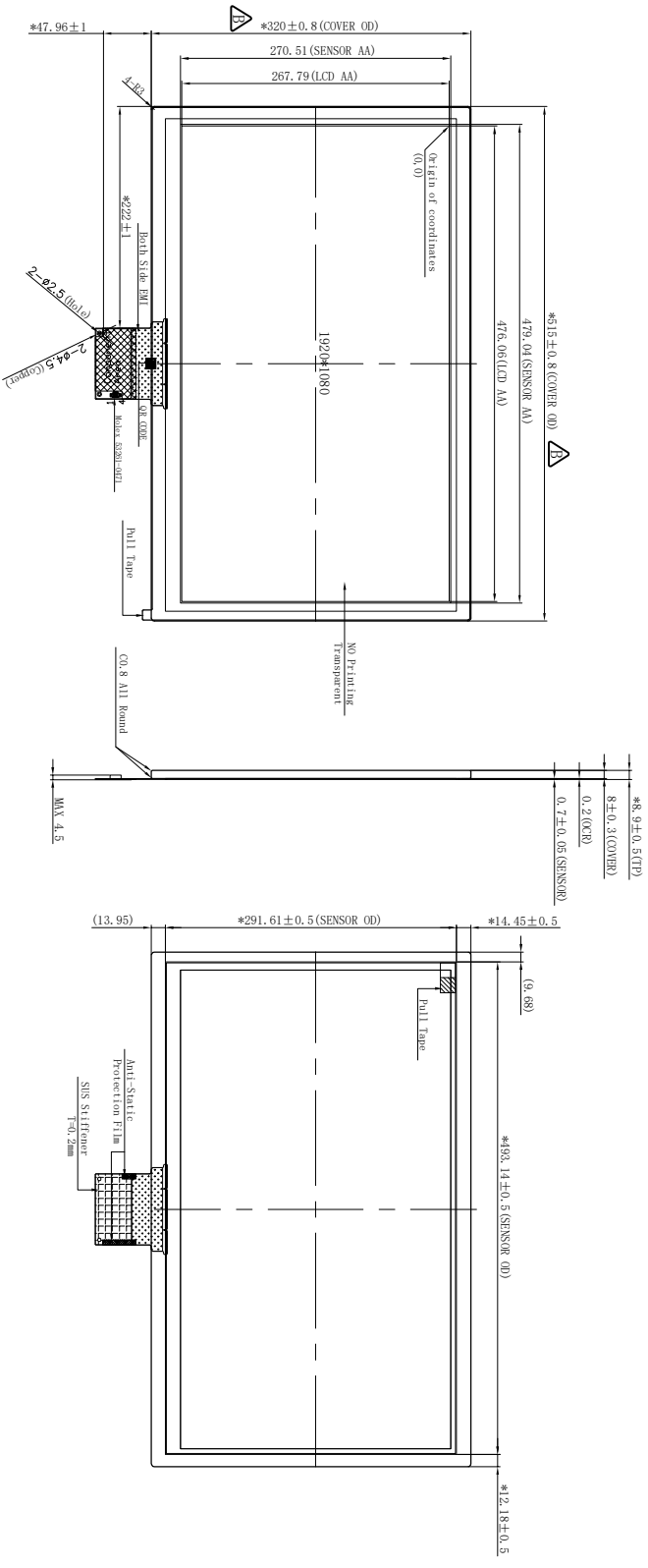


TECHNOLOGY CHARACTERISTICS CTP	
PROPERTY	Requirement
STRUCTURE	G+G
Bonding Type	/
TOUCH IC	mXT2952TD-C21R001
NO. OF TOUCH	10
Coverglass Thickness	8.0mm (Sodalime)
ITO Glass Thickness	0.7um
Surface Hardness	≥6H
Light Transmittance	85% Min
Operating Temperature	-20~70° C
Storage Temperature	-30~80° C



Front view

Side view

Back view

USB PIN DEFINITION	
Pin No.	Definition
1	VCC 5V
2	D-
3	D+
4	GND

**NOTES:**  
 \*: Important dimensions  
 TOLERANCE UNLESS: x. x±0.3  
 OTHERWISE SPECIFIED: x.xx±0.2  
 DIMENSIONS IN MM: ANGULAR: ±1°

**ROHS**

VER.	SYMBOL	AMENDMENT	SIGN	DATE	SHEET 1 OF 1
3.0		Modify Cover OD: Cancel link printing	Lee	2019.10.30	
2.0		Change ic to mXT2952TD-C2U001	Lee	2019.10.16	
1.0		First issue	Lee	2019.10.09	

TITLE	
MODULE SPEC.	
Drawing NO: CT0454-V3.0	
Product NO:FN215A021-V1.0	
Project No: TPA5267	



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